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(12) **United States Design Patent**  
**Itakura et al.**

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(54) **SEMICONDUCTOR PACKAGE**

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(\*\*) Term: **15 Years**

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**Related U.S. Application Data**

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**Foreign Application Priority Data**

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(52) **U.S. Cl.**  
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(58) **Field of Classification Search**

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361/679.01, 713, 728, 736, 760, 761, 772,  
361/775, 783, 820; 174/250, 253;  
438/15, 25, 26, 51, 55, 63, 64, 106  
CPC . H01L 21/00; H01L 2224/42; H01L 2224/43;  
H01L 2021/00; H01L 2021/02; H01L  
2021/04; H01L 21/4814; H01L 21/4846;  
H01L 21/4871; H01L 21/67144; H01L  
23/02; H01L 23/13; H01L 23/14; H01L

23/147; H01L 2924/171; H01L  
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(Continued)

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PC

(57) **CLAIM**

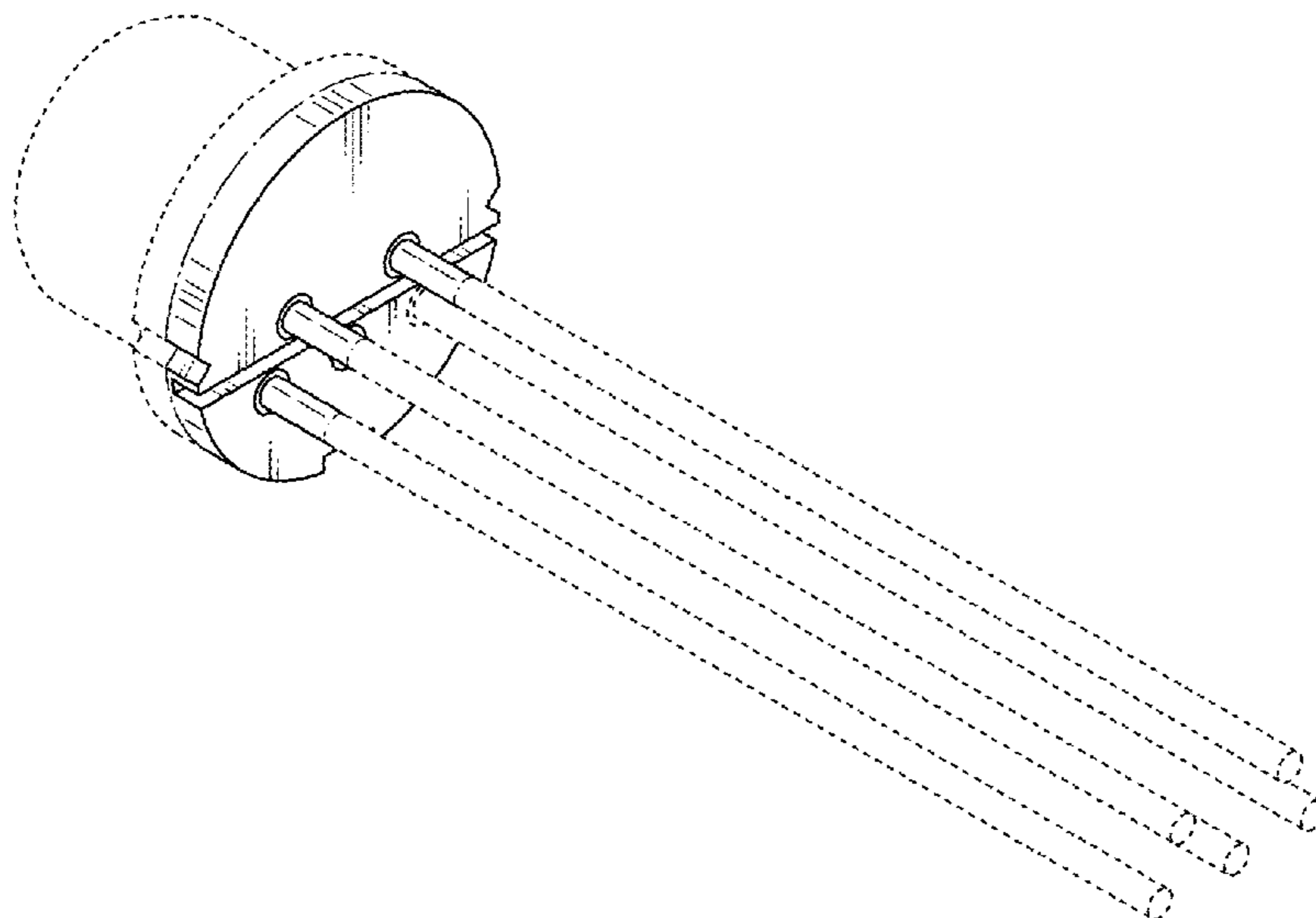
The ornamental design for a semiconductor package, as shown and described.

**DESCRIPTION**

FIG. 1 is a front, top and left side perspective view of a semiconductor package showing our new design;  
FIG. 2 is a front view thereof;  
FIG. 3 is a rear view thereof;  
FIG. 4 is a top view thereof;  
FIG. 5 is a bottom view thereof;  
FIG. 6 is a left side view thereof;  
FIG. 7 is a right view thereof;  
FIG. 8 is a cross-sectional view taken along line 8-8 in FIG. 2, with the internal structure shown in broken lines; and,  
FIG. 9 is a perspective view of FIG. 1, shown in a state of use.

The parts shown in even dashed broken lines do not form part of the claimed design. The dot and dashed lines mean a boundary between the claimed portion and the non-claimed portion and form no part of the claimed design.

**1 Claim, 6 Drawing Sheets**



(58) **Field of Classification Search**

CPC ..... 2924/1811; H01L 2924/1815; H01L  
2924/19042; H01L 2924/1905; H01L  
2224/08054; H01L 23/58; H05B 41/14;  
H02B 6/4201; G02B 6/4256; G02B  
6/4257; G02B 6/4261; G02B 6/4262;  
G02B 6/428; G02B 6/4281; H05K 1/14;  
H05K 1/141; H05K 1/142; H05K 1/144;  
H05K 1/18; H05K 1/181; H05K 1/182;  
H05K 1/026

See application file for complete search history.

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Fig. 1

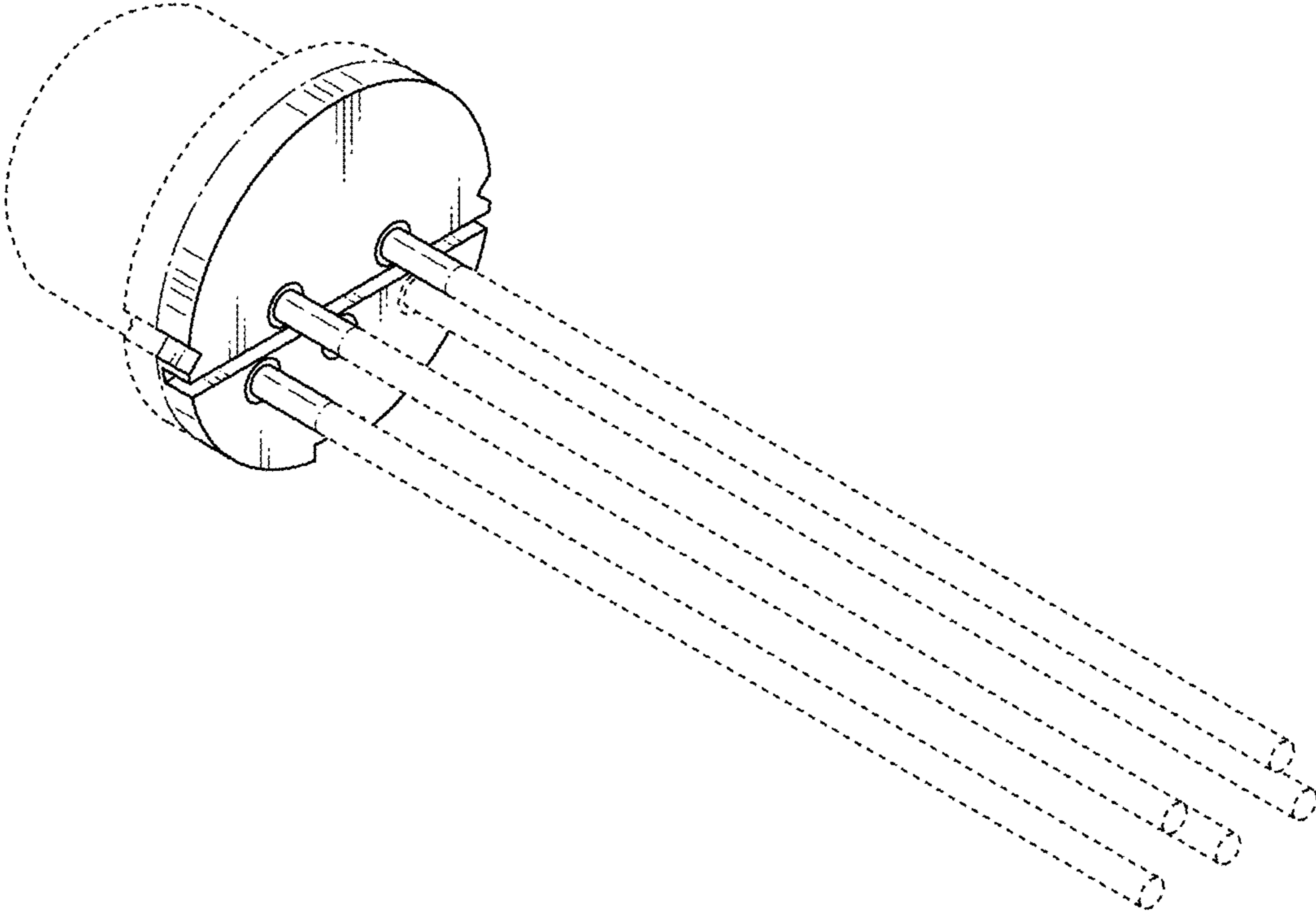


Fig. 2

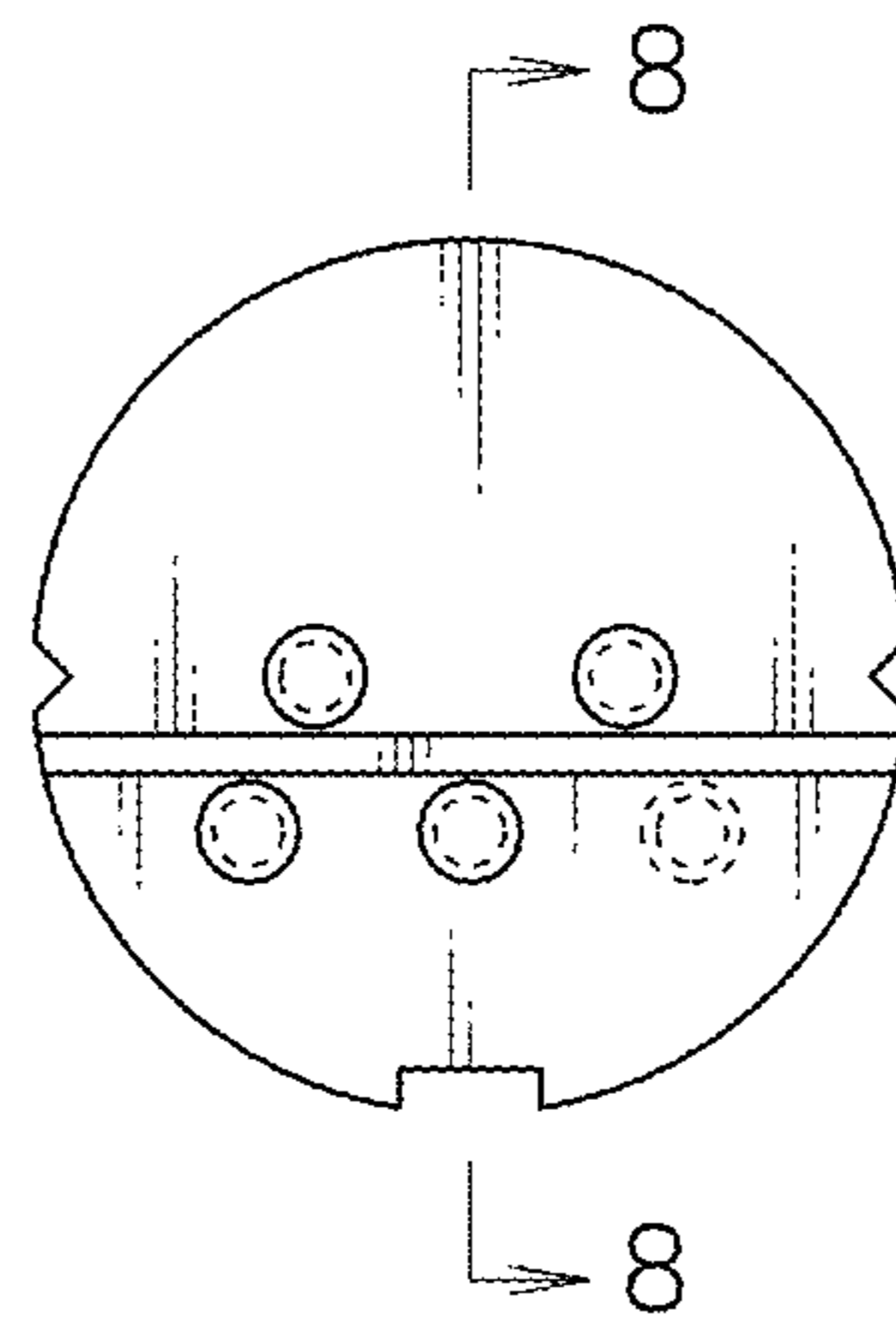


Fig. 3

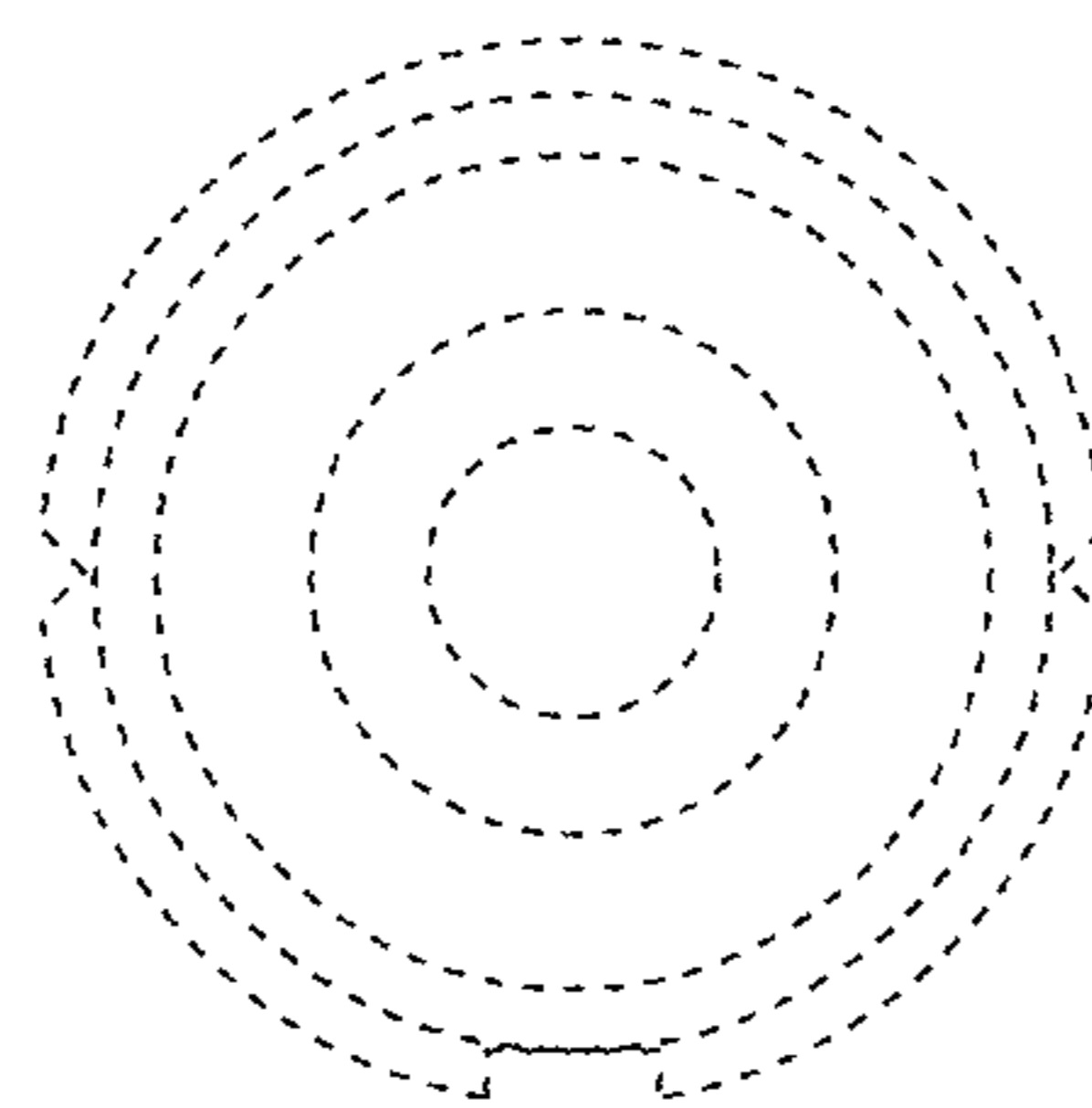


Fig. 4

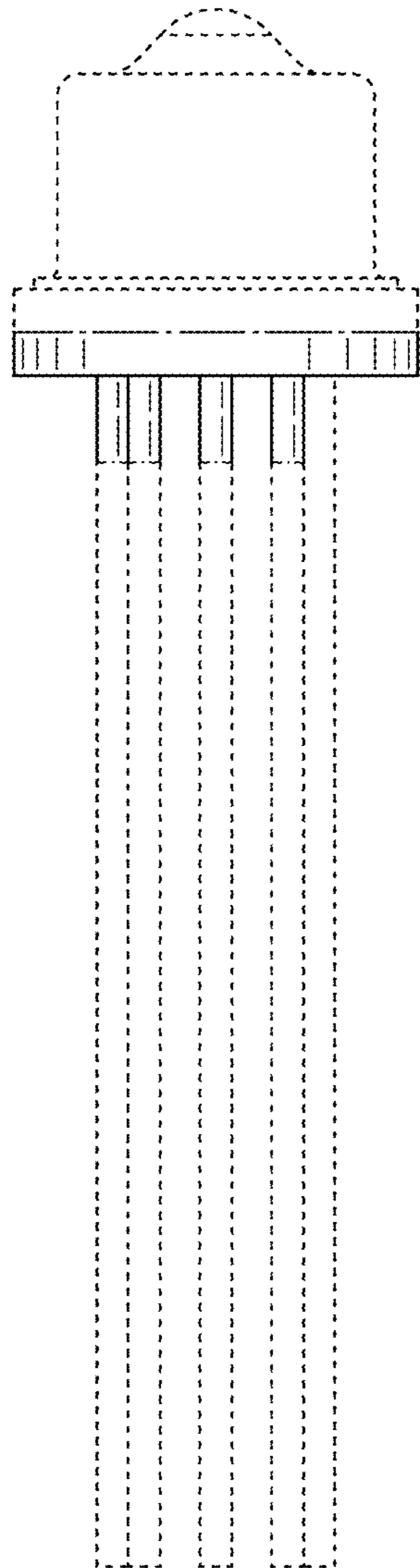


Fig. 5

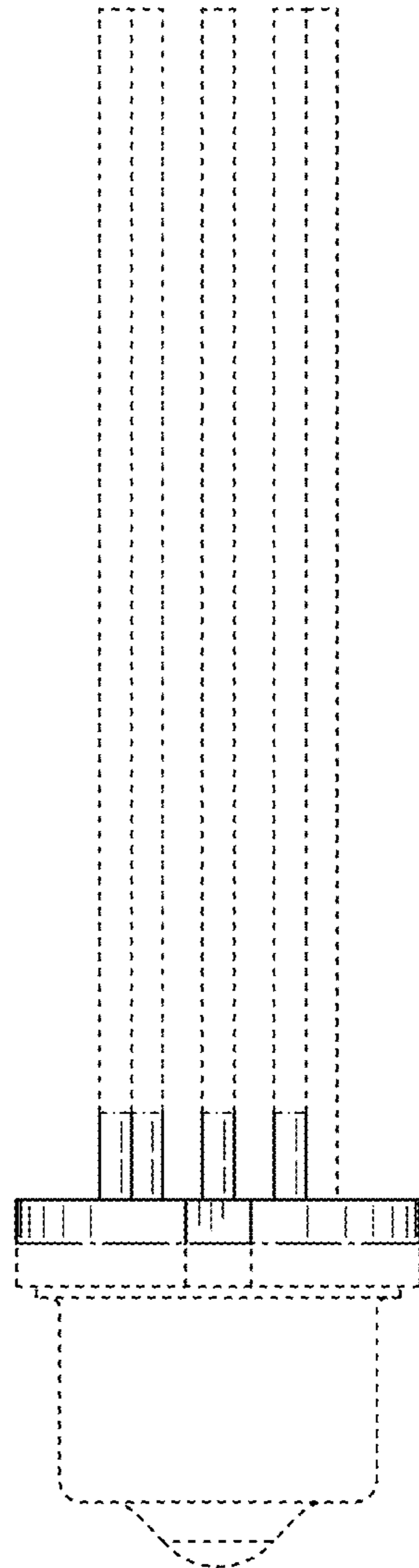


Fig. 6

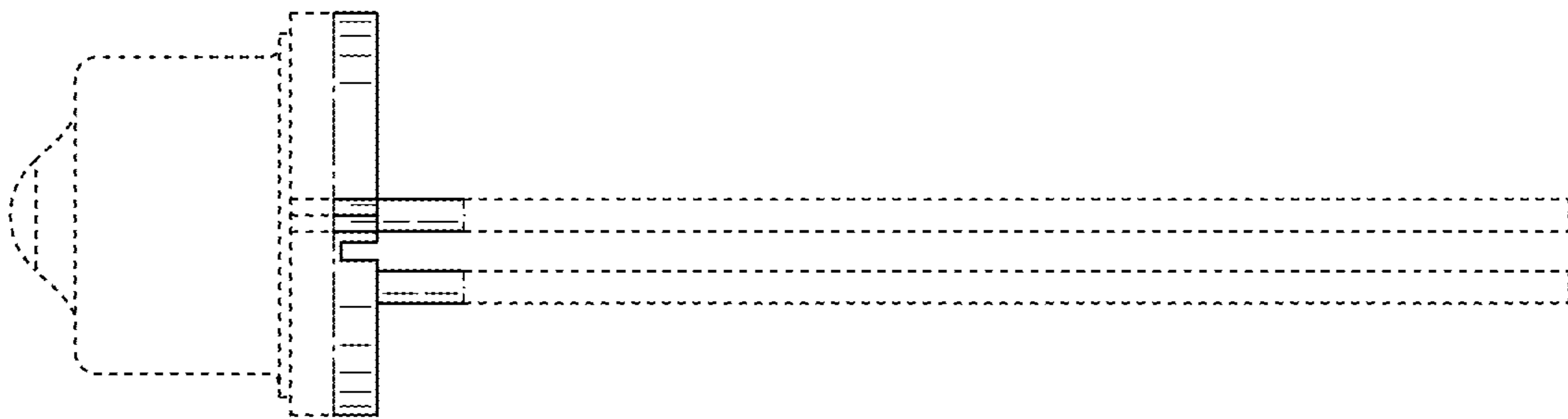


Fig. 7

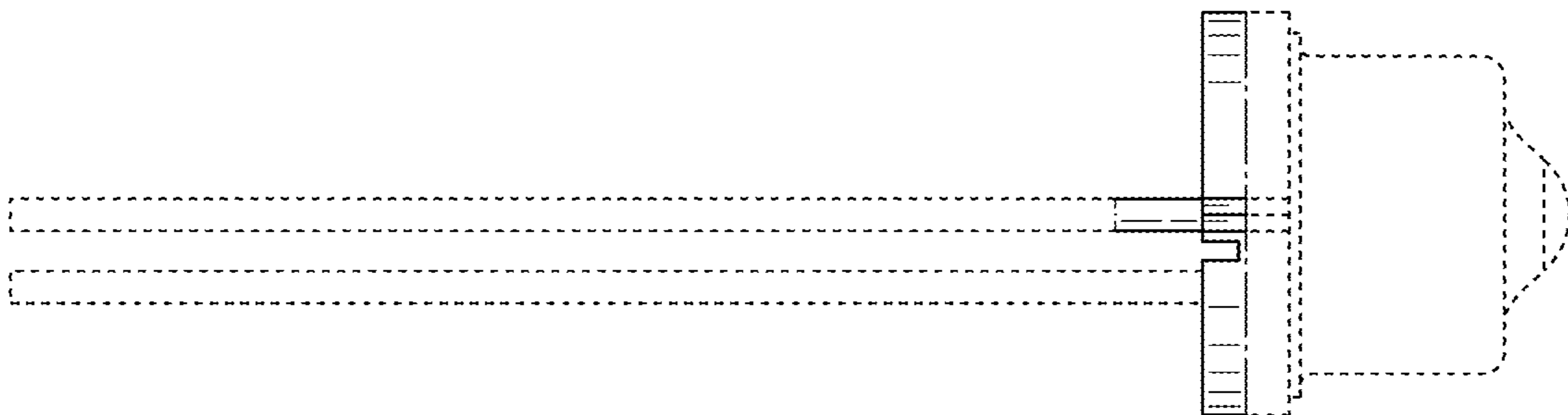


Fig. 8

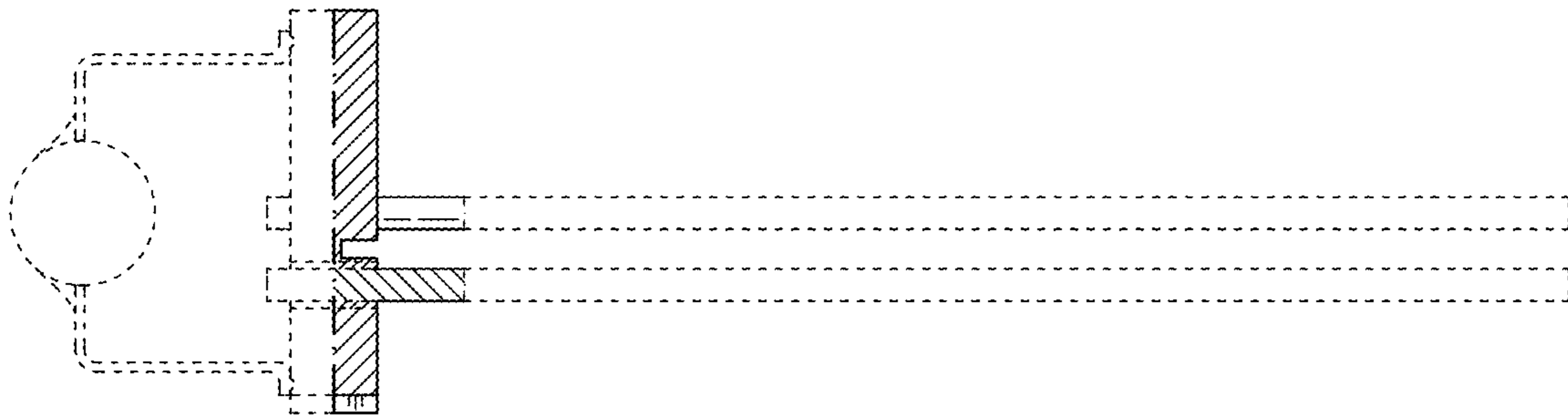


Fig. 9

